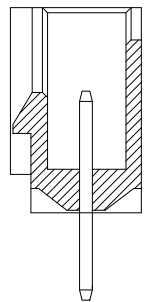
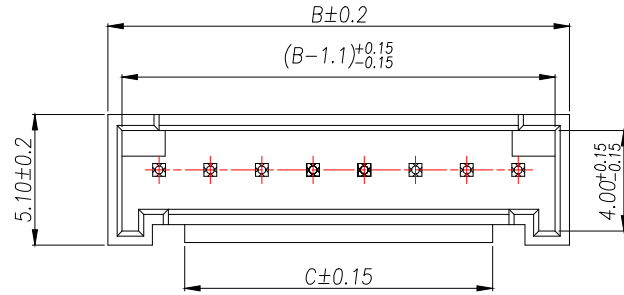


REV.	Q'TY	ECN. NO.	APR.	DATE

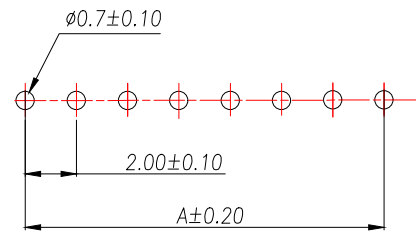
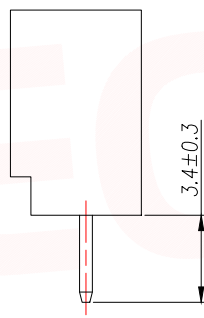
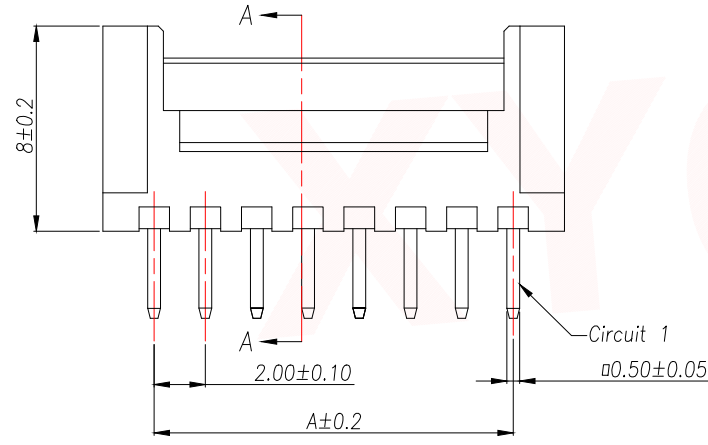
PRELIMINARY  
DESIGN IS SUBJECT  
TO CHANGE WITHOUT  
PRIOR NOTICE



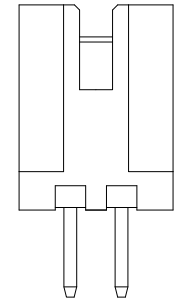
SECTION A-A

- 技术要求:
1. 塑件材料: PA66
  2. 接触件: 黄铜镀锡
  3. 接触电阻:  $\leq 10m\Omega$
  4. 绝缘电阻:  $\geq 1000M\Omega$
  5. 额定电压: 250V AC DC
  6. 额定电流: 2.0A AC DC
  7. 耐压: 能承受 1000V AC/Min ute
  8. 工作温度:  $-25^{\circ}\sim\sim+85^{\circ}$
  9. 可焊性试验: 浸锡面积  $\geq 95\%$  温度  $220^{+5}_{-0}$ , 时间  $2.5\pm 0.5$  秒
  10. 铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B	C
XY-HY2.0-2A11	2	2	6	/
XY-HY2.0-3A11	3	4	8	2
XY-HY2.0-4A11	4	6	10	4
XY-HY2.0-5A11	5	8	12	6
XY-HY2.0-6A11	6	10	14	8
XY-HY2.0-7A11	7	12	16	10
XY-HY2.0-8A11	8	14	18	12
XY-HY2.0-9A11	9	16	20	14
XY-HY2.0-10A11	10	18	22	16
XY-HY2.0-11A11	11	20	24	18
XY-HY2.0-12A11	12	22	26	20
XY-HY2.0-13A11	13	24	28	22
XY-HY2.0-14A11	14	26	30	24
XY-HY2.0-15A11	15	28	32	26



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)



2P外观

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X±0.35	X.*± 5°	APR.	Alex	TITLE: WAFER 2.0mm H8.0mm 180° DIP
.XX±0.25	.X.*± 3°	CHK.	Jack	DWG NO. XY-HY2.0-NA11
.XXX±0.15	.XX.*± 1°	DRA.	Can	PROJ.  CUSTOMER DRAWING
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	